3.2 Bill of Material

Table 2. Bill of Materials

Count	RefDes	Value	Description	Size	Part Number	Mfr
1	C1	0.47uF	Capacitor, Ceramic, 10V, X5R, 10%	0402		
1	C2	1uF	Capacitor, Ceramic, 6.3V, X5R, 10%	0402		
4	J1, J4, J6, J7	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
4	J2, J3, J8, J9	PEC36SAAN	Header, Male 3-pin, 100mil spacing	0.100 inch x 3	PEC36SAAN	Sullins
1	J5	ED555/3DS	Terminal Block, 3-pin, 6-A, 3.5mm	0.41 x 0.25 inch	ED555/3DS	OST
1	J10	22-05-3041	Header, Friction Lock Ass'y, 4-pin Right Angle	0.400 x 0.500	22-05-3041	Molex
1	R1	14.7k	Resistor, Chip, 1/16-W, 5%	0402	Std	Std
1	R2	10k	Resistor, Chip, 1/16-W, 5%	0402	Std	Std
2	R3, R4	5.1k	Resistor, Chip, 1/16-W, 5%	0402	Std	Std
4	TP1, TP7, TP9	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
7	TP2, TP3, TP11, TP12	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone
3	TP4, TP5, TP6, TP10	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	U1	bq27421YZF-G1x	IC, Battery Monitor and Data Logger	DSBGA	bq27421-G1x	TI

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